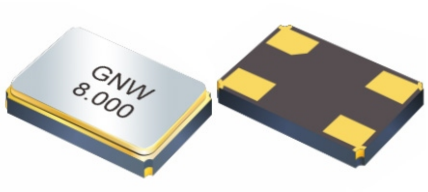
3.2×2.5 SMD Crystal



APPLICATIONS

- Bluetooth / Wireless LAN
- Wearable Devices
- LTE / SAS

FEATURE

- Rugged AT-cut crystal construction
- Miniature 3.2×2.5mm ceramic package
- Anti-EMI design
- Tight Tolerance and Stability
- Reflow Soldering/Emboss Taping

Electrical Specifications 电气参数

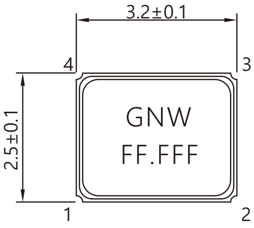
项目	Item/Type	Electrical Specifications
频率范围	Frequency Range	8MHz to 100MHz
调整频差	Frequency Tolerance(△F)(at 25℃)	±10ppm to ±30ppm
温度频差	Frequency Drift	±10ppm to ±30ppm
工作温度范围	Operating Temperature Range	-20℃ ~ +70℃,-40℃ ~ +85℃ or -40℃ ~ +105℃
储存温度范围	Storage Temperature Range	-55℃ ~ +125℃
老化	Aging (25℃)	±3ppm/year max.
静电容	Shunt Capacitance (C0)	3pF max.
激励功率	Drive Level	10μW Typical
绝缘阻抗	Insulaton Resistance (Rs)	500 Megaohms min. at D.C 100V
负载电容	Load Capacitance (CL)	8,10,12pF or specify

Equivalent Series Resistance and Mode of Operation 等效阻抗和振荡模式

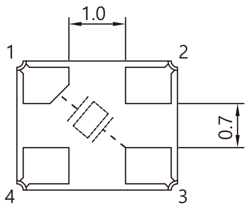
Frequency Range 频率范围	ESR (Ω) 等效阻抗	Mode 振荡模式
8~12MHz	200Ω max.	Fundamental
12~16MHz	100Ω max.	Fundamental
16~20MHz	80Ω max.	Fundamental
20~24MHz	60Ω max.	Fundamental
24~64MHz	40Ω max.	Fundamental
54~100MHz	40Ω max.	3rd overtone

Mechanical Dimensions 外型尺寸

Units:mm

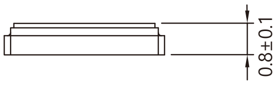


Top View

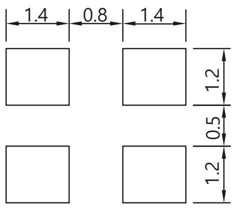


Bottom View

Pin Connection	
#1,#3	Crystal
#2,#4	GND



Side View



Land Pattern